

Small Signal MOSFET

115 mAmps, 60 Volts

N-Channel SOT-23

- We declare that the material of product are Halogen Free and compliance with RoHS requirements.
- ESD Protected:1000V

MAXIMUM RATINGS

| Rating | Symbol | Value | Unit |
|---|---|------------------------------------|------------|
| Drain-Source Voltage | V _{DSS} | 60 | Vdc |
| Drain-Gate Voltage ($R_{GS} = 1.0 \text{ M}\Omega$) | V _{DGR} | 60 | Vdc |
| Drain Current – Continuous $T_C = 25^\circ\text{C}$ (Note 1.) $T_C = 100^\circ\text{C}$ (Note 1.) – Pulsed (Note 2.) | I _D I _D I _{DM} | ± 115 ± 75 ± 800 | mAdc |
| Gate-Source Voltage – Continuous – Non-repetitive ($t_p \leq 50 \mu\text{s}$) | V _{GS} V _{GSM} | ± 20 ± 40 | Vdc Vpk |

THERMAL CHARACTERISTICS

| Characteristic | Symbol | Max | Unit |
|---|-----------------------------------|----------------|----------------------------|
| Total Device Dissipation FR-5 Board (Note 3.) $T_A = 25^\circ\text{C}$ Derate above 25°C | P _D | 225 1.8 | mW mW/ $^\circ\text{C}$ |
| Thermal Resistance, Junction to Ambient | R _{θJA} | 556 | $^\circ\text{C}/\text{W}$ |
| Total Device Dissipation Alumina Substrate,(Note 4.) $T_A = 25^\circ\text{C}$ Derate above 25°C | P _D | 300 2.4 | mW mW/ $^\circ\text{C}$ |
| Thermal Resistance, Junction to Ambient | R _{θJA} | 417 | $^\circ\text{C}/\text{W}$ |
| Junction and Storage Temperature | T _J , T _{stg} | -55 to +150 | $^\circ\text{C}$ |

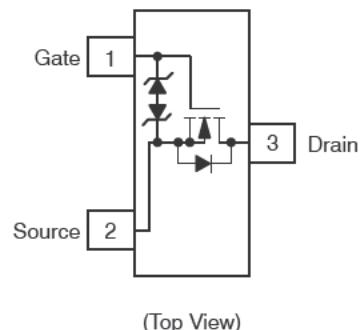
- The Power Dissipation of the package may result in a lower continuous drain current.
- Pulse Test: Pulse Width $\leq 300 \mu\text{s}$, Duty Cycle $\leq 2.0\%$.
- FR-5 = $1.0 \times 0.75 \times 0.062 \text{ in.}$
- Alumina = $0.4 \times 0.3 \times 0.025 \text{ in}$ 99.5% alumina.

ORDERING INFORMATION

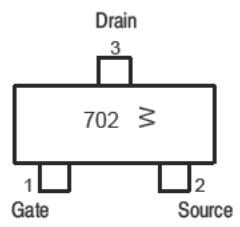
| Device | Marking | Shipping |
|-------------|---------|-------------------|
| L2N7002LT1G | 702 | 3000 Tape & Reel |
| L2N7002LT3G | 702 | 10000 Tape & Reel |

L2N7002LT1G


Simplified Schematic



MARKING DIAGRAM & PIN ASSIGNMENT



702 = Device Code
W = Month Code

L2N7002LT1G

ELECTRICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$ unless otherwise noted)

| Characteristic | Symbol | Min | Typ | Max | Unit |
|----------------|--------|-----|-----|-----|------|
|----------------|--------|-----|-----|-----|------|

OFF CHARACTERISTICS

| | | | | | |
|---|---------------|----|---|------------|-----------------|
| Drain-Source Breakdown Voltage ($V_{GS} = 0$, $I_D = 10 \mu\text{Adc}$) | $V_{(BR)DSS}$ | 60 | – | – | Vdc |
| Zero Gate Voltage Drain Current ($V_{GS} = 0$, $V_{DS} = 60 \text{ Vdc}$) | I_{DSS} | – | – | 1.0 500 | μAdc |
| Gate-Body Leakage Current, Forward ($V_{GS} = 20 \text{ Vdc}$) | I_{GSSF} | – | – | 1 | μAdc |
| Gate-Body Leakage Current, Reverse ($V_{GS} = -20 \text{ Vdc}$) | I_{GSSR} | – | – | -1 | μAdc |

ON CHARACTERISTICS (Note 2.)

DYNAMIC CHARACTERISTICS

| | | | | | |
|--|-----------|---|-----|-----|----|
| Input Capacitance ($V_{DS} = 25$ Vdc, $V_{GS} = 0$, f = 1.0 MHz) | C_{iss} | – | 17 | 50 | pF |
| Output Capacitance ($V_{DS} = 25$ Vdc, $V_{GS} = 0$, f = 1.0 MHz) | C_{oss} | – | 10 | 25 | pF |
| Reverse Transfer Capacitance ($V_{DS} = 25$ Vdc, $V_{GS} = 0$, f = 1.0 MHz) | C_{rss} | – | 2.5 | 5.0 | pF |

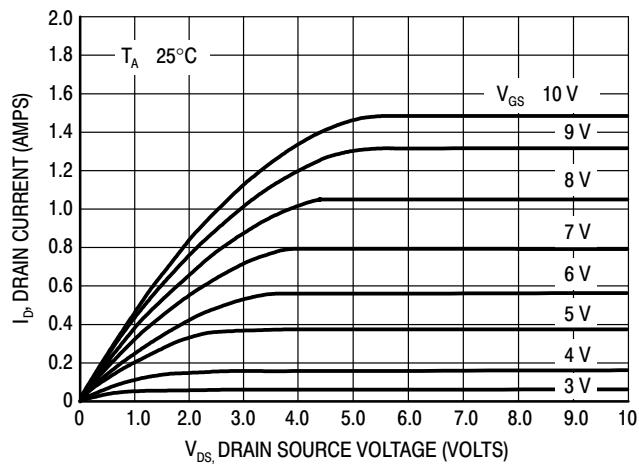
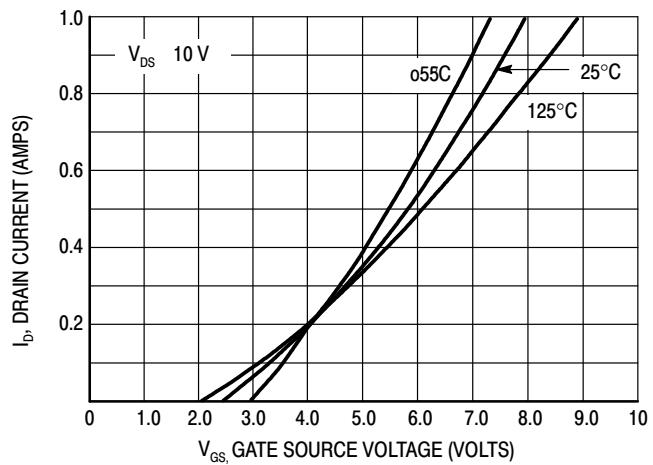
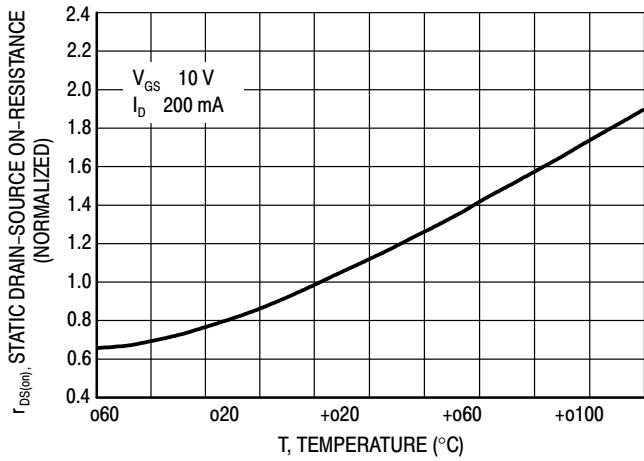
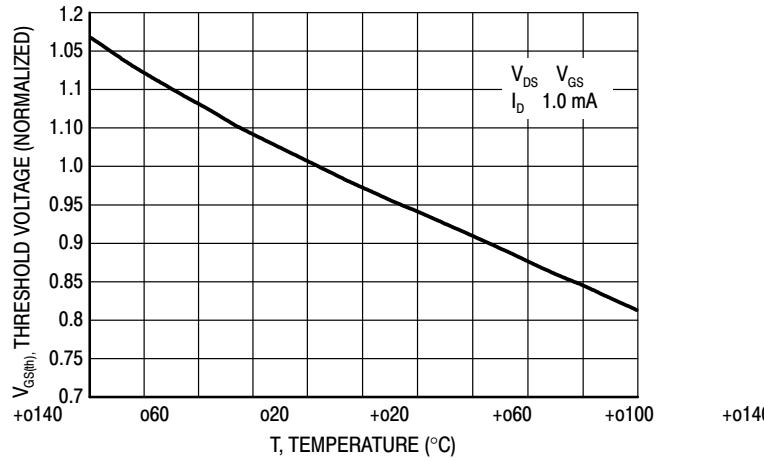
SWITCHING CHARACTERISTICS (Note 2.)

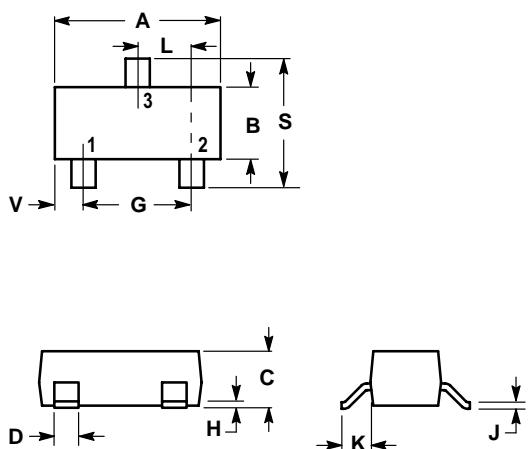
| | | | | | | |
|---------------------|---|--------------|---|----|----|----|
| Turn-On Delay Time | $(V_{DD} = 25 \text{ Vdc}, I_D \approx 500 \text{ mA}, R_G = 25 \Omega, R_L = 50 \Omega, V_{gen} = 10 \text{ V})$ | $t_{d(on)}$ | - | 7 | 20 | ns |
| Turn-Off Delay Time | | $t_{d(off)}$ | - | 11 | 40 | ns |

BODY-DRAIN DIODE RATINGS

| | | | | | |
|---|----------|---|---|------|-----|
| Diode Forward On-Voltage ($I_S = 115$ mA, $V_{GS} = 0$ V) | V_{SD} | - | - | -1.5 | Vdc |
| Source Current Continuous (Body Diode) | I_S | - | - | -115 | mA |
| Source Current Pulsed | I_{SM} | - | - | -800 | mA |

2. Pulse Test: Pulse Width \leq 300 μ s, Duty Cycle \leq 2.0%.

L2N7002LT1G
TYPICAL ELECTRICAL CHARACTERISTICS

Figure 1. Ohmic Region

Figure 2. Transfer Characteristics

Figure 3. Temperature versus Static Drain-Source On-Resistance

Figure 4. Temperature versus Gate Threshold Voltage

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SOT-23

NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982
2. CONTROLLING DIMENSION: INCH.

| DIM | INCHES | | MILLIMETERS | |
|-----|--------|--------|-------------|-------|
| | MIN | MAX | MIN | MAX |
| A | 0.1102 | 0.1197 | 2.80 | 3.04 |
| B | 0.0472 | 0.0551 | 1.20 | 1.40 |
| C | 0.0350 | 0.0440 | 0.89 | 1.11 |
| D | 0.0150 | 0.0200 | 0.37 | 0.50 |
| G | 0.0701 | 0.0807 | 1.78 | 2.04 |
| H | 0.0005 | 0.0040 | 0.013 | 0.100 |
| J | 0.0034 | 0.0070 | 0.085 | 0.177 |
| K | 0.0140 | 0.0285 | 0.35 | 0.69 |
| L | 0.0350 | 0.0401 | 0.89 | 1.02 |
| S | 0.0830 | 0.1039 | 2.10 | 2.64 |
| V | 0.0177 | 0.0236 | 0.45 | 0.60 |

